

NUMBER 316130

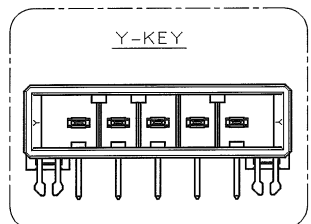
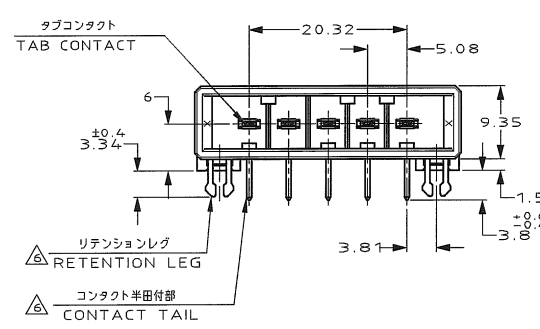
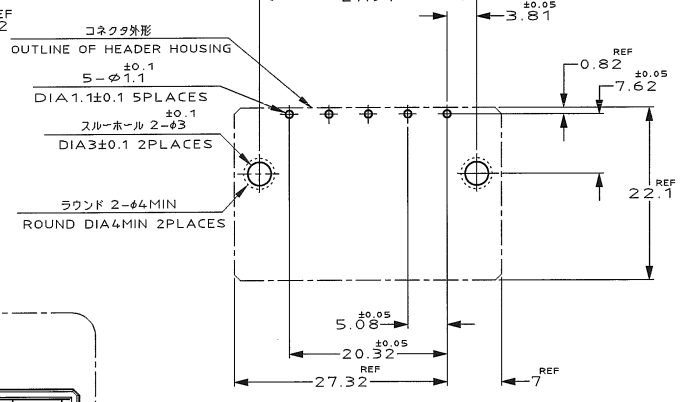
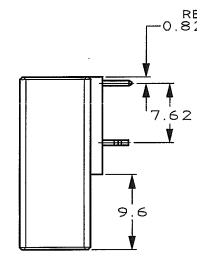
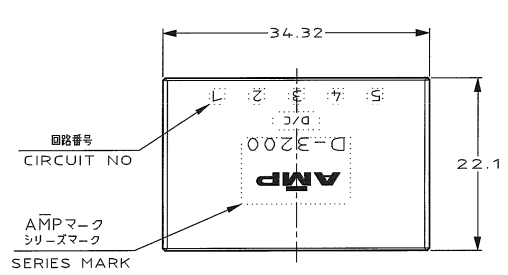
3rd ANGLE PROJECTION

METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

AMP-1 REV.10/93



推奨基板取付け寸法  
PC 基板厚: 1.6±0.1  
(非累積公差)  
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
PC BOARD THICKNESS: 1.6±0.1  
(NOT ACCUMULATE TOLERANCE)  
(CONNECTOR MOUNT SIDE)

△	△	2-316130-5	Y	OBsolete
△	△	2-316130-3	Y	
△	△	2-316130-2	Y	
△	△	1-316130-5	X	
△	△	1-316130-3	X	
△	△	1-316130-2	X	
		(FINISH)	製法番号 (PART NO.)	KEY

- NOTES
- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER  
CONTACT: COPPER ALLOY  
RETENTION LEG: COPPER ALLOY
  - FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER NI PLATING
  - FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER NI PLATING
  - FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
  - FINISH (RETENTION LEG): TIN LEAD PLATED
  - FINISH (RETENTION LEG): TIN PLATED
  - FINISH (CONTACT TAIL): OVER NICKEL
  - OBsolete PARTS: OBsolete CIS STREAMLINING PER D.RENAUD/D.SINISI

- 注記
- 材料: ハウジング: ガラス入り熱可塑性  
ポリエスチル樹脂  
コンタクト: 銅合金  
リテンションレグ: 銅合金
  - めっき: コンタクト: 全面Ni下地  
鍍膜厚: 0.38 μm MIN 金めっき
  - めっき: コンタクト: 全面Ni下地  
鍍膜厚: 0.76 μm MIN 金めっき
  - めっき: コンタクト: 全面Ni下地  
鍍膜厚: 2.0 μm MIN スズめっき
  - めっき: リテンションレグとコンタクト半田付部
  - めっき: ニッケル下地の土にスズめっき

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**tyco Electronics** Tyco Electronics AMP K.K. Kawasaki, Japan

WIRE RANGE: mm7(AWG - ) INSULATION DIA: mmφ

NAME: 5 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200

B1	ECO-10-000445	KK	AEG	JAN10			
B	REVISED(FJD0-0039-03)	TS	SM	25	APR	93	
A	REVISED(FJD0-0114-03)	TS	SM	25	APR	93	
O	RELEASED (FJ00-2557-95)	KI	YI	31	JUL	95	
LTR	REVISION RECORD	DR	CHK	DATE	CHK.	DATE	APP.
					Y. ISHIKAWA	31 JUL 95	S. MANGA BE

GENERAL TOLERANCE: 100% ±0.2, 100% 30% ±0.3, 20% 100% ±0.4, 23%

SIZE: A3 LOC: J NUMBER: 316130

SCALE: 2-1 REV: B1 SHEET: 1 OF 1

(CUSTOMER DRAWING) 顧客用図面